Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model [List multiple models if applicable.]
MSA1500 / AA986A
MSA1510i / AD537A

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	22
Batteries	All types including standard alkaline and lithium coin or button style batteries	4
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		4
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips type driver	# 1

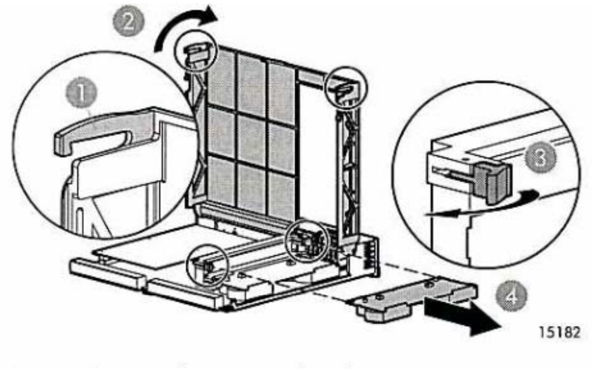
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

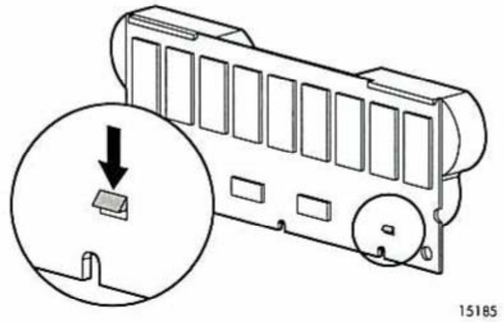
1. Batteries: Remove controllers from the front of the enclosure. Only 1 controller may be present as the other is optional. Open the cover of the controller to expose the memory DIMM located on the right side of the controller as viewed from the midplane connector side. A single DIMM is standard, a second DIMM is optional. There are 2 Ni-MH battery packs per DIMM. Remove the DIMM from the controllers. The battery packs should be removed by disengaging the plastic latch from the DIMM's PCA which is located by the connector. (See attachment 1)
2. 2.5 CM capacitors: Remove power supplies and open with a #1 Phillips screw driver. Remove the circuit board and pry the caps from the PCB with a flat blade screwdriver.(See attachment 2)
3.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

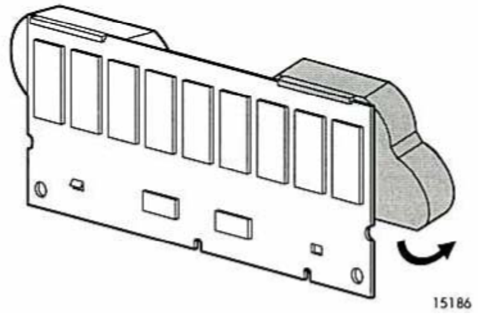
Attachment 1.



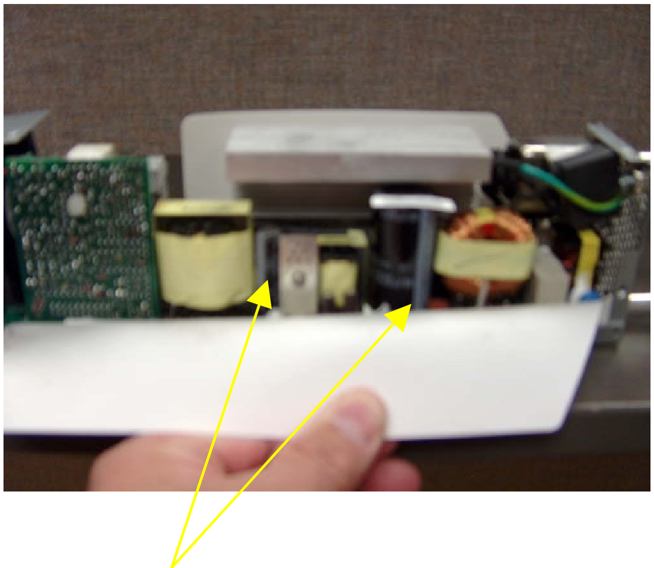
1. Push down on the battery retaining clip, located near the lower corner of the module.



2. Swing the battery pack away from the module to a 30-degree angle, and then lift the battery pack upward to unhook the top of it.



Attachment 2:



Capacitors to be removed